



Material Content Data Sheet



Sales Product Name		SPD06N80C3		Issued		20. July 2018		
MA#		MA000453260						
Package		PG-TO252-3-311		Weight*		316.39 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.945	1.56	1.56	15628	15628
leadframe	non noble metal	iron	7439-89-6	0.143	0.05		453	
	inorganic material	phosphorus	7723-14-0	0.043	0.01		136	
	non noble metal	copper	7440-50-8	143.098	45.22	45.28	452286	452875
wire	non noble metal	aluminium	7429-90-5	5.491	1.74	1.74	17357	17357
encapsulation	inorganic material	antimonytrioxide	1309-64-4	1.899	0.60		6002	
	plastics	brominated resin	-	2.035	0.64		6431	
	organic material	carbon black	1333-86-4	2.170	0.69		6860	
	plastics	epoxy resin	-	18.312	5.79		57879	
	inorganic material	silicondioxide	60676-86-0	111.229	35.16	42.88	351560	428732
leadfinish	non noble metal	tin	7440-31-5	3.787	1.20	1.20	11969	11969
plating	non noble metal	nickel	7440-02-0	0.086	0.03		273	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.03	1	274
solder	noble metal	silver	7440-22-4	0.099	0.03		312	
	non noble metal	tin	7440-31-5	0.079	0.02		249	
	non noble metal	lead	7439-92-1	3.769	1.19	1.24	11911	12472
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		61	
	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	copper	7440-50-8	19.177	6.06	6.07	60614	60693
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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